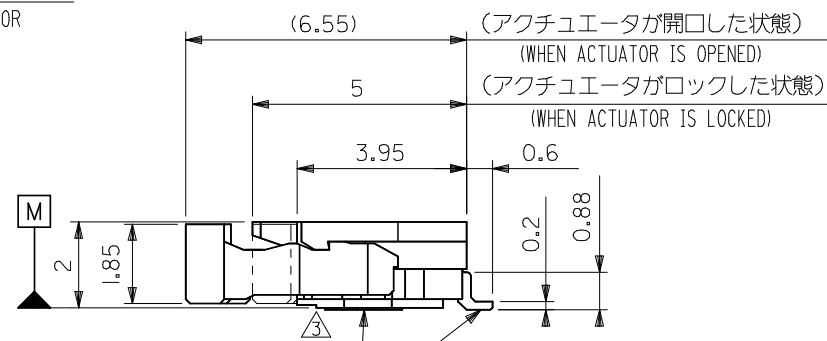
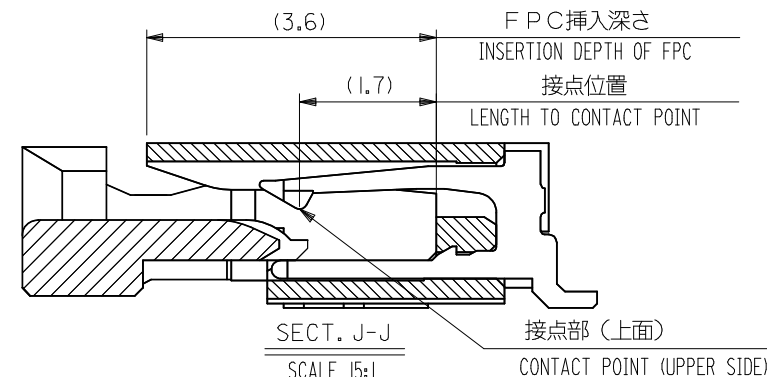
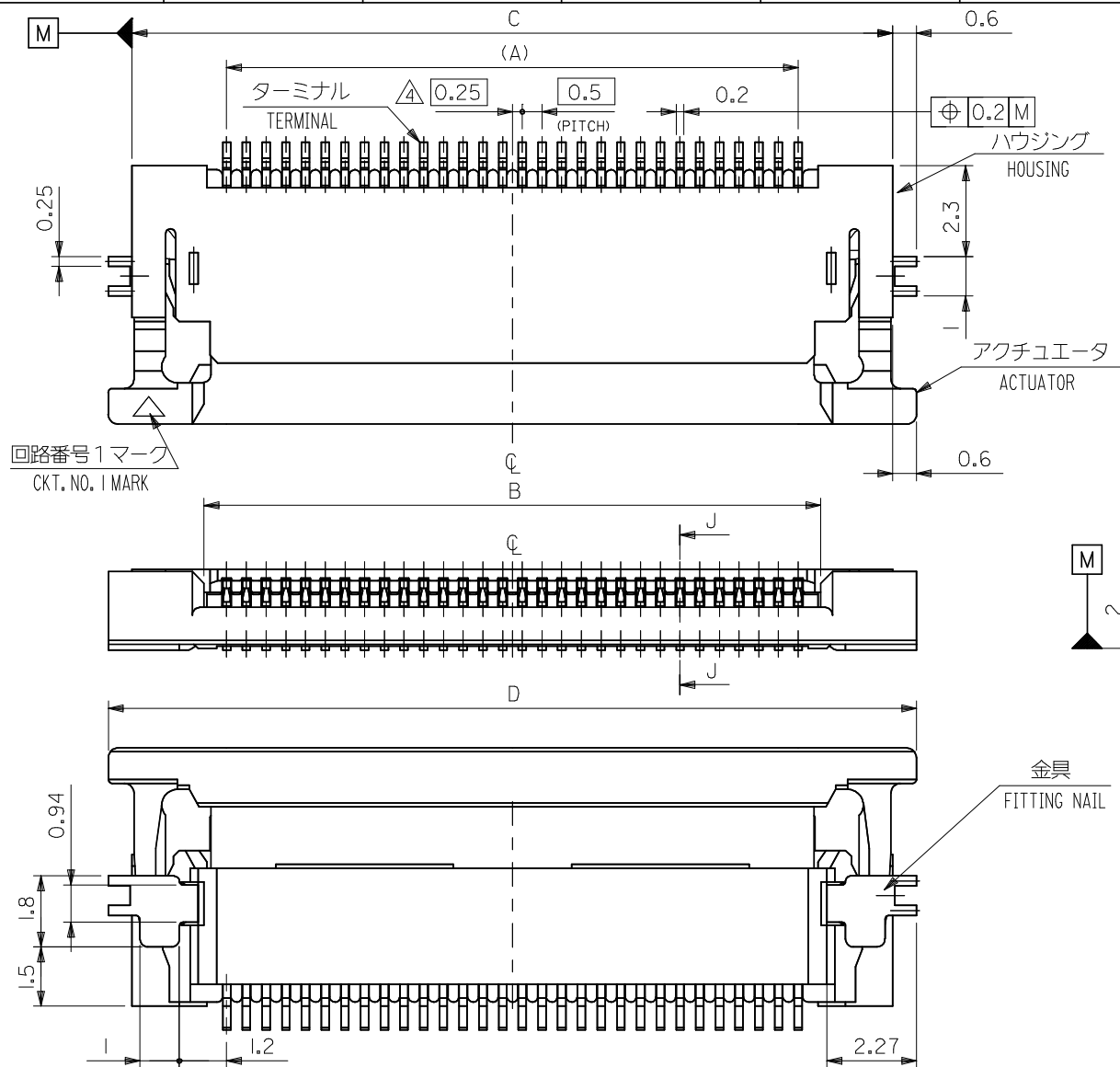
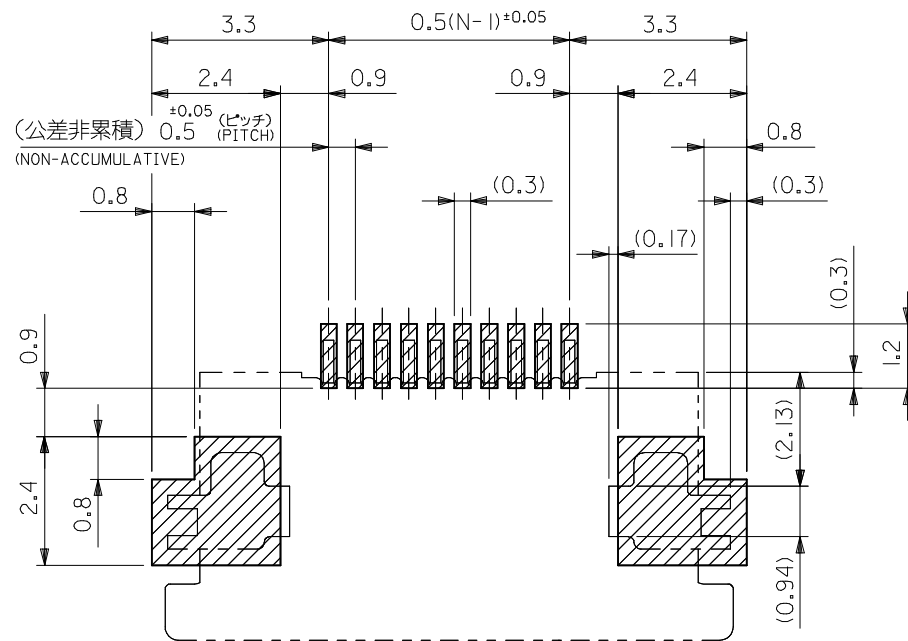




30.5	29.3	25.65	24.5	54104-5096	54104 - 5039	50
28.5	27.3	23.65	22.5	54104-4696	54104 - 4639	46
28.0	26.8	23.15	22.0	54104-4596	54104 - 4539	45
27.0	25.8	22.15	21.0	54104-4396	54104 - 4339	43
25.5	24.3	20.65	19.5	54104-4096	54104 - 4039	40
24.5	23.3	19.65	18.5	54104-3896	54104 - 3839	38
23.5	22.3	18.65	17.5	54104-3696	54104 - 3639	36
23.0	21.8	18.15	17.0	54104-3596	54104 - 3539	35
22.5	21.3	17.65	16.5	54104-3496	54104 - 3439	34
22.0	20.8	17.15	16.0	54104-3396	54104 - 3339	33
21.5	20.3	16.65	15.5	54104-3296	54104 - 3239	32
20.5	19.3	15.65	14.5	54104-3096	54104 - 3039	30
D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	CIRCUIT
				ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:MMABEI CHK'D:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		---	METRIC			
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE					
		30 OVER	± 0.3	APPROVED BY	DATE	molex MOLEX INCORPORATED				
		ANGULAR ±3 °	M. SASAO	'04/01/22						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
SEE TABLE				SD-54104-071		1 OF 2				
A		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



コネクタ位置
CONNECTOR POSITION

参考基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)

(マウント面)
(MOUNTING SIDE)

注記 NOTES

I. 使用材料 MATERIAL

ハウジング : 46ナイロン、UL94V-0
HOUSING 46NYLON

アクチュエータ : PPS、UL94V-0
ACTUATOR

ターミナル
TERMINAL :リン青銅、ニッケル下地 錫ビスマスメッキ (t=0.2)
PHOS-BRONZE, TIN-BISMUTH

金具 :リン青銅、ニッケル下地 錫メッキ (t=0.2)
FITTING NAIL PHOS-BRONZE,TIN OVER NICKEL PLATING.(t=0.2)

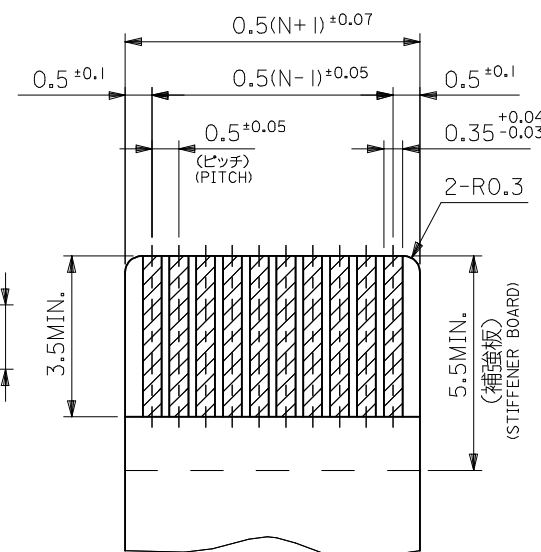
2. エンボステーパ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54104-***39 SHOULD BE LOCKED.

△ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX.、下方向 0.15 MAX. とし、相互のバラツキ量は、0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1 MAX. H

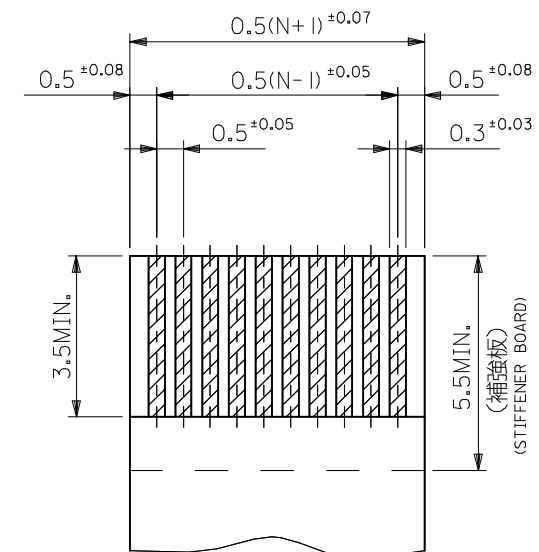
△ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△5 パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

6. 本製品は 54104-**37 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54104-**37.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3^{±0.03})
(THICKNESS: 0.3^{±0.03})



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり)厚さ: $0.3^{+0.03}$
(THICKNESS: $0.3^{+0.03}$)

FPC/FFCについて

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル
メッキ厚 3～9マイクロメートル錫または半田メッキ（電気メッキ）

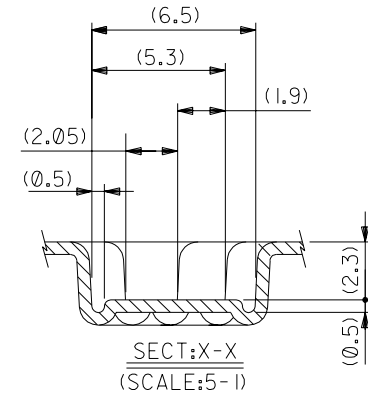
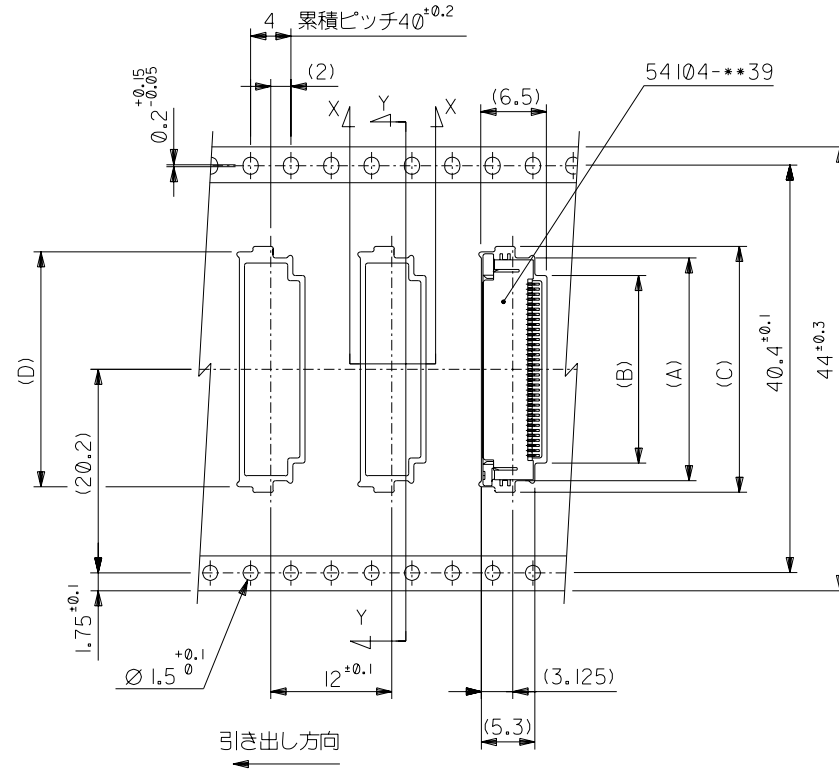
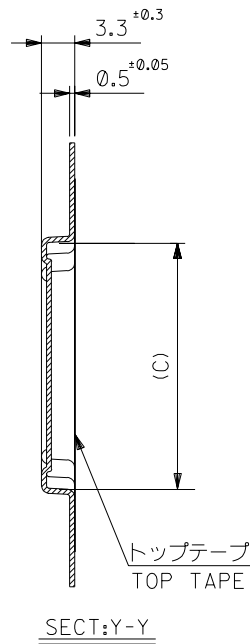
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL:
35 micrometer or 50 micrometer
TIN OR SOLDER PLATING:
3 ~ 9 micrometer(ELECTRICAL PLATING)

FPCについて

補強フィルム材質はポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。

RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

FREE OF 54104-***39		54104-***39		MODEL NO.	
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	
DESIGN UNITS METRIC		THIRD ANGLE PROJECTION			
DRAWN BY DATE Y. SAKIYAMA '04/01/22		CHECKED BY DATE M. SASAO '04/01/22		APPROVED BY DATE M. SASAO '04/01/22	
MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



EC NO.
DRWN:
CHK:
APPR:

EC NO.
DRWN:
CHK:
APPR:

EC NO.
DRWN:
CHK:
APPR:

REVISED '04/04/21
EC NO. J2004-3918
DRWN: Y.WADA
CHK: M.SASAO
APPR: M.SASAO

RELEASED '04/01/22
EC NO. J2004-2032
DRWN: Y.SAKIYAMA
CHK: M.SASAO
APPR: M.SASAO

DESCRIPTION

MATERIAL
材料

SHEET 1 OF 2 参照
REFER TO SHEET 1 OF 2

FINISH
仕上げ

WIRE RANGE
適用電線範囲

REV

INS. RANGE
被覆外径

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
一般公差

10 UNDER
未満

±0.2

10 OVER 30 UNDER
以上 未満

±0.25

30 OVER
以上

±0.3

ANGLE 角度

±3°

SCALE

MODEL NO.
DESIGN UNITS
☑mm ☐INCH

DRAWN BY & DATE
Y.SAKIYAMA '04/01/22

CHECKED BY & DATE
M.SASAO '04/01/22

APPROVED BY & DATE
M.SASAO '04/01/22

CAD FILENAME
SD-54104-072.S02

54104-***96

THIRD ANGLE
PROJECTION

TITLE: Embstp Pkg for
0.5 FPC Conn Zif Hsg Assy
-LEAD FREE-

MOLEX INCORPORATED

MATERIAL NO.
SEE CHART

DRAWING NO.
SD-54104-072

SHEET NO.
2 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

SIZE
B